AUTOMOTIVE

ROHS

HALOGEN

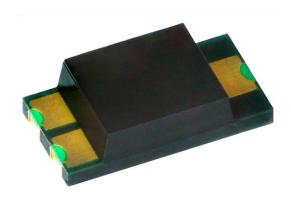
FREE

GREEN (5-2008)



Vishay Semiconductors

Silicon PIN Photodiode



DESCRIPTION

VEMD6110X01 is a high speed and high sensitive PIN photodiode. It is a small surface mount device (SMD) including the chip with a 0.85 mm² sensitive area and a daylight blocking filter matched with IR emitters operating at wavelength of 830 nm to 950 nm.

FEATURES

- Package type: surface mount
- Package form: 1206
- Dimensions (L x W x H in mm): 4 x 2 x 1.05
- Radiant sensitive area (in mm²): 0.85
- · High photo sensitivity
- · High radiant sensitivity
- Daylight blocking filter matched with 830 nm to 950 nm emitters
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 60^{\circ}$
- Floor life: 72 h, MSL 4, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



· High speed photo detector

PRODUCT SUMMARY				
COMPONENT	I _{ra} (μΑ)	φ (deg)	λ _{0.5} (nm)	
VEMD6110X01	9.5	± 60	750 to 1050	

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VEMD6110X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	1206		

Note

· MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	32	V	
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW	
Junction temperature		T _j	110	°C	
Operating temperature range		T _{amb}	-40 to +110	°C	
Storage temperature range		T _{stg}	-40 to +110	°C	
Soldering temperature	Acc. reflow solder profile fig. 8	T _{sd}	260	°C	
Thermal resistance junction/ambient	Acc. J-STD-051	R _{thJA}	270	K/W	

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F		1		V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	32			V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}		1	3	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _D		12		pF
	$V_R = 5 V, f = 1 MHz, E = 0$	C _D		3.6		pF
Open circuit voltage	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	Vo		356		mV
Temperature coefficient of Vo	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK _{Vo}		-3.1		mV/K
Short circuit current	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	l _k		9		μΑ
Temperature coefficient of Ik	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	TK _{lk}		0.1		%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	6.7	9.5	12.4	μΑ
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ_{p}		950		nm
Range of spectral bandwidth		λ _{0.5}	750		1050	nm
Rise time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _r		100		ns
Fall time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _f		100		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

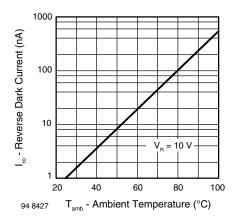


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

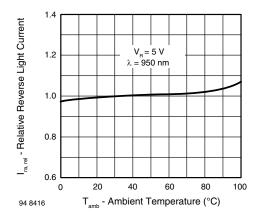


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

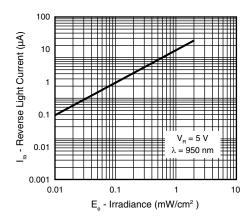


Fig. 3 - Reverse Light Current vs. Irradiance

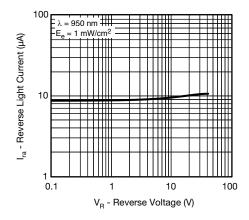


Fig. 4 - Reverse Light Current vs. Reverse Voltage

REFLOW SOLDER PROFILE

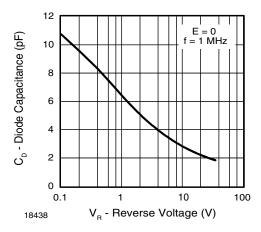


Fig. 5 - Diode Capacitance vs. Reverse Voltage

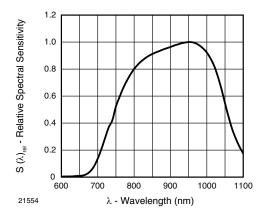


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

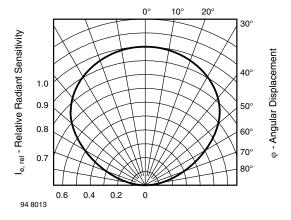


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

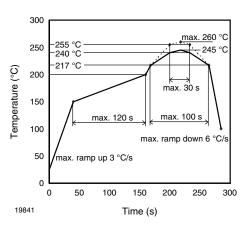


Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 72 h

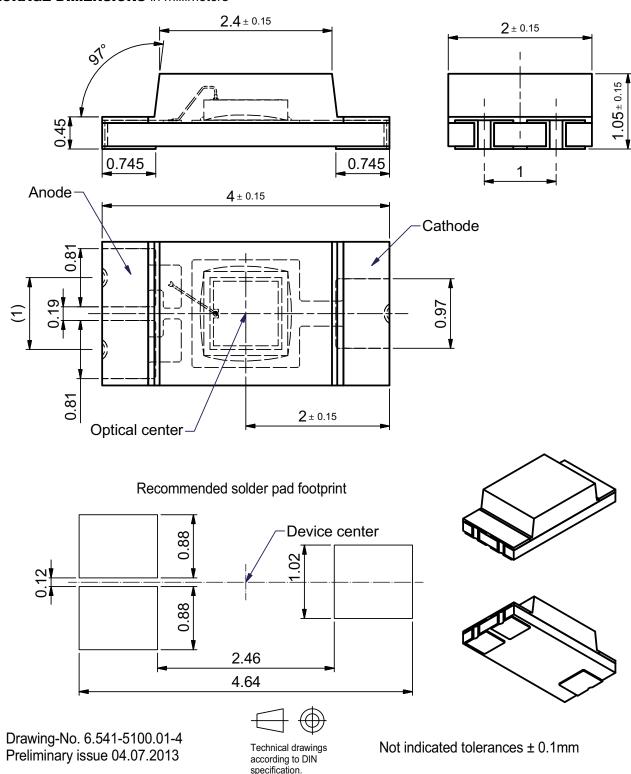
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 4, acc. to J-STD-020.

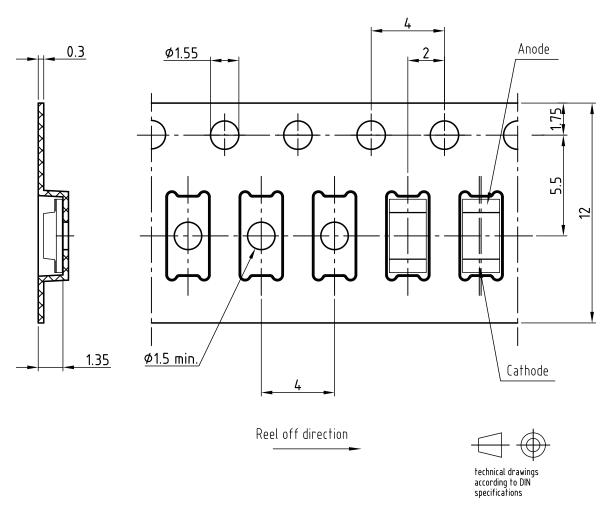
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters



BLISTER TAPE DIMENSIONS in millimeters



Not indicated tolerances ±0.1

Drawing refers to following Types: TEMD6010FX01

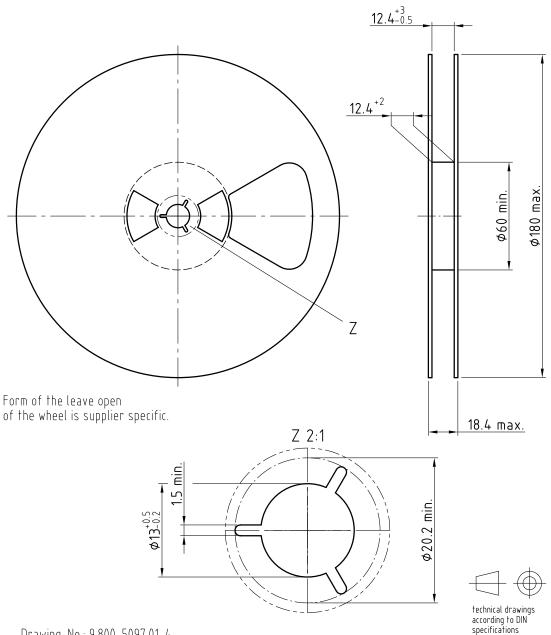
VEMD6x10X01 VEMD6x15X01

Drawing-No.: 9.700-5329.02-4

Prel Issue: 16.07.2013

All dimensions in mm

REEL DIMENSIONS in millimeters



Drawing-No.: 9.800-5097.01-4

Issue: 1; 05.05.08

20874



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